

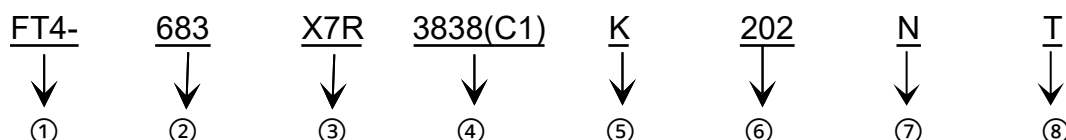
“Military Screening” Grade Two Multi Layer Ceramic Capacitors



1. Features

- Rectangular, serialized size specifications, suitable for surface mount of hybrid integrated circuits or printed circuits;
- Lead type: radial lead, suitable for plug-in and wave soldering;
- There are a variety of end electrode lead-out materials for Ag (Cu)-Ni-Sn, which are especially suitable for the strict requirements of surface assembly technology for weldability and welding heat resistance.;
- Low inductance, low loss, good frequency characteristics, high reliability;
- National military standard production line production;
- Widely used in military communications, radar, artillery fuzes, ships, ground electronic equipment for aviation, aerospace, and weapon systems, and high-end civilian equipment.
- It is suitable for resonance circuits, coupling circuits and circuits that require low loss, high capacitance, stability and high insulation resistance in various types of military electronic equipment.

Purtnumber structure



Description:

① Product series.

FL4: Class I dielectric material type (COG)

FT4: Class II dielectric material type (Other TCC).

② Rated capacity code.

Capacity code	Actual value (pF)	Remark
0R5	0.5pF	The first two digits are valid figures, and the last digit is a power of 10.
1R0	1.0pF	
472	47×10^2	
104	10×10^4	

③ Dielectric material.

Our company has C0G, X7R, X5R, Y5V, Z5U and other materials.

④ Size and leads shape.

Dimensions	0805	1206	1210	1808	1812	2220	2225	3838
Lmax(mm)	4.2	5.5	5.5	8.5	8.5	10.5	10.5	12.0
Wmax(mm)	3.8	4.5	5.5	6.5	6.5	8.5	9.5	12.0
Tmax(mm)	3.8	3.8	3.8	3.8	3.8	4.2	4.2	4.0

⑤ Capacity tolerance level

code	A	B	C	D.	f	G	J	K	M
tolerance	±0.05pF	±0.10pF	±0.25pF	±0.50pF	±1.0%	±2.0%	±5.0%	±10.0%	±20.0%
Remark	A, B, C, D tolerance level is generally used for ≤10pF capacity								

⑥ Rated voltage

Voltage code	Actual value (V)	Remark
6R3	6.3	The first two digits are valid figures, and the last digit is 10 index of R as decimal point
500	50×10 ⁰	
201	20×10 ¹	
102	10×10 ²	
202	20×10 ²	

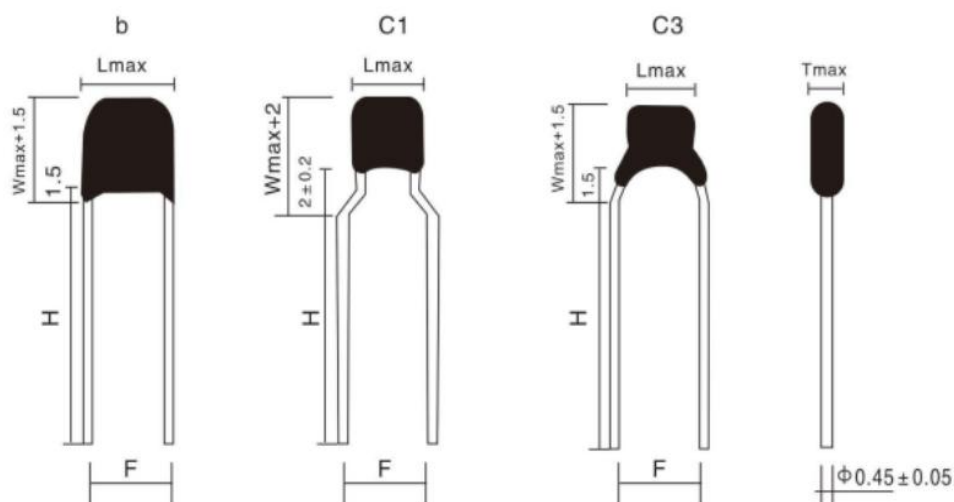
⑦ Terminal plating

Terminal plating type	Plating Code
Three-layer plating Ag(Cu)/Ni/Sn	N
Silver	S

⑧ Packaging type

Packaging type	Packaging Code
Bulk	B
Taping	T

Size and Leads shape specifications



model		Dimensions (mm)				
British system	Leads shape	f	h	L	W	Tmax
0805	b	2.54±0.50	≥10.0	≤4.2	≤3.8	≤3.8
	C1	5.08±0.50	≥5.0/10.0			
	C3	5.08±0.50	≥5.0/10.0			
1206	b	3.50±0.50	≥10.0	≤5.5	≤4.5	≤3.8
	C1	5.08±0.50				
1210	b	3.50±0.50	≥10.0	≤5.5	≤5.5	≤3.8
	C1	5.08±0.50				
1808/1812	b	4.57±0.50	≥10.0	≤8.5	≤6.5	≤3.8
2220	b	5.70±0.50	≥10.0	≤10.5	≤8.5	≤4.2
2225	b	5.70±0.50	≥10.0	≤10.5	≤9.5	≤4.2
3838	b	10.3±0.50	≥10.0	≤12.0	≤12.0	≤4.0

Remarks: Products that meet customer needs can be designed according to customer's special requirements.

Conventional voltage product capacity range

Specification	0402					0603					0805					1206				
(V)	6.3	10	16	25	50	6.3	10	16	25	50	6.3	10	16	25	50	6.3	10	16	25	50
C _R																				
100pF																				
220pF																				
330pF																				
470pF																				
680pF																				
1 nF																				
2.2nF																				
4.7nF																				
5.6nF																				
6.8nF																				
10nF																				
15nF																				
22nF																				
27nF																				
33nF																				
39nF																				
47nF																				
56nF																				
68nF																				
100nF																				
150nF																				
220nF																				
270nF																				
330nF																				
470nF																				
820nF																				
1.0uF																				
2.2uF																				
4.7uF																				
6.8uF																				
10uF																				
22uF																				
27uF																				
33uF																				
47uF																				
100uF																				

 X7R

 X5R

7. Medium and high voltage product capacity range

Specification	0	0805			1206					1210				
(V)	1	100	200	250	100	250	500	1000	2000	100	250	500	1000	2000
C _R														
100pF														
150pF														
330pF														
470pF														
680pF														
1000pF														
1. 2nF														
1. 5nF														
2. 2nF														
3. 3nF														
4. 7nF														
6. 8nF														
10nF														
12nF														
15nF														
22nF														
27nF														
33nF														
39nF														
47nF														
56nF														
68nF														
100nF														
120nF														
150nF														
220nF														
270nF														
330nF														
470nF														
560nF														
1. 0uF														
2. 2uF														

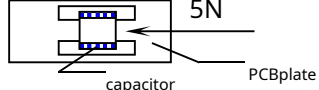
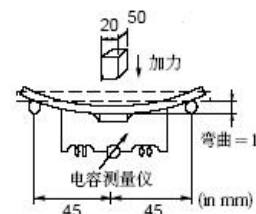
Specification	1808						1812						
(V) C _R	100	250	500	1000	2000	3000	100	250	500	1000	2000	3000	4000
100pF													
150pF													
330pF													
470pF													
680pF													
1000pF													
1. 5nF													
2. 2nF													
2. 7nF													
3. 3nF													
4. 7nF													
6. 8nF													
10nF													
12nF													
15nF													
22nF													
27nF													
33nF													
39nF													
47nF													
56nF													
68nF													
100nF													
120nF													
150nF													
220nF													
270nF													
330nF													
470nF													
2. 2uF													

Specification	2225						
(V) CR	100	250	500	1000	2000	3000	4000
100pF							
150pF							
180pF							
220pF							
330pF							
470pF							
680pF							
1000pF							
1. 5nF							
2. 2nF							
3. 3nF							
4. 7nF							
6. 8nF							
10nF							
12nF							
15nF							
22nF							
27nF							
33nF							
39nF							
47nF							
56nF							
68nF							
100nF							
120nF							
150nF							
220nF							
270nF							
330nF							
470nF							
820nF							
1uF							
2. 2uF							

Note: When customers have special requirements, please specify when ordering.

Product Specifications

project	technical specifications						Test Methods						
range of working temperature	Class I	C0G: -55 ~ +125°C											
	Class II	X7R: -55 ~ +125°C											
		X5R: -55 ~ +85°C Y5V: -30 ~ +85°C Z5U: +10 ~ +85°C											
Exterior	no obvious defects						Visual inspection						
Capacitance	Class I	within specification error						Nominal capacity	test frequency	Test voltage	ambient temperature		
								≤1000pF	1MHz±10%	1.0±0.2Vrms	25±2°C		
								>1000pF	1KHz±10%				
	Class II	within specification error						≤10μF	1KHz±10%	1.0±0.2Vrms			
								>10μF	120±24Hz	0.5±0.1Vrms			
								Z5U	1.0±0.1KHz	0.5±0.05Vrms			
loss tangent (DF) Dissipation Factor	Class I	Cap≤50pF,DF≤1.5×(150/CR+7)×10-4;Cap≥50pF,DF≤0.15%							High volume products 5 suffix DF≤7.5% 6 suffix DF≤10.0% The rest 0603 And capacitor products below 0603 DF≤10.0%				
	Class II	额定电压	≥100V	50V	25V	16V	10V	6.3V					
		X7R	≤2.5%	≤3.5% (C≤1μF)	≤5.0% (C≤1μF)	≤5.0% (C≤3.3μF)	≤7.5% (C≤3.3μF)						
		X5R		≤5.0% (C>1μF)	≤7.5% (C>1μF)	≤10.0% (C>3.3μF)	≤10.0% (C≥3.3μF)						
		Y5V	≥25V	25V>UR≥6.3V									
		Z5U	≤7.0% (C≤1μF)	≤12.5%									
Insulation resistance (IR) Insulation Resistance	Class I	C≤10nF,Ri≥10000MΩ C>10nF,R*CR≥100S						额定电压	测试电压	测试时间	充放电电流	环境	
	Class II	X7R	C≤25nF,Ri≥4000MΩ C>25nF,R*CR>100S						Ur<500V	Ur	60±5sec	≤50mA	温度25±2℃ 湿度<75%
		X5R											
		Y5V	C≤25nF,Ri≥4000MΩ C>25nF,R*CR>100S						Ur≥500V	500V	60±5sec	≤50mA	
Dielectric strength (DWW) Dielectric Withstanding Voltage	There should be no dielectric breakdown or damage						Rated voltage	Test voltage	time	Charge and discharge current			
							Ur<200V	2.5Ur	1~5sec	≤50mA			
							200V≤Ur≤1000V	1.5Ur	1~5sec				
							Ur>1000V	1.2Ur	1~5sec				
capacity temperature coefficient or temperature characteristics	Class I	C0G: 0±30ppm/℃						preprocessing (Ilkind):150+0/-10℃,1hrs,placetwenty four±2hrsAfter the initial measurement in the following temperature sequence, the temperature stabilized30minpost-determination (△CbyT3prevail)					
								step	temperature (°C)				
								T1	20±2				
	Class II	X7R:≤±15% X5R:≤±15% Y5V: +22%~-82% Z5U: +22%~-56%						T2	lower class temperature (eg X7R -55±3)				
								T3	20±2				
								T4	upper class temperature (eg X7R +125±2)				
Solderability	Exterior	No visible damage, tin rate ≥ 95%						Soak the capacitor in the solution of ethanol and rosin (accounting for 25% by weight), take it out and preheat it at a temperature of 80-120℃ for 10-30 seconds, and then immerse it in the solder solution. Dipping temperature: 235±5℃; Dipping speed: 25±0.25mm/s Dipping time: 2±0.5sec					

Resistance to soldering heat	Exterior	No visible damage, tin rate ≥ 95%	Soak the capacitor in a solution of ethanol and rosin (accounting for 25% by weight), take it out and preheat it at a temperature of 100-200°C for 10±2min, and then immerse it in the solder solution. Immersion tin temperature:260±5°C; Immersion tin speed:25±0.25mm/s Dipping time:5±1sec After taking it out, clean it with solvent, and then10observed under a microscope at a magnification of magnification. After the test, place it indoors for 24±2hrs before measuring.																	
	Δ C/C	Iclass: ≤±0.5%or±0.5pF, whichever is greater IIclass: X7R, X5R : -5~+10% Y5V ,Z5U: -10~+20%																		
	DF	same as original standard																		
	IR	same as original standard																		
terminal electrode Adhesion strength	The terminal electrodes are not peeled off, and the appearance has no visible damage		Apply thrust:5N time:10±1sec speed:1mm/sec																	
Bending strength	Exterior	no visible damage	Test substrate:PCB Bending Depth:1mm																	
	Δ C/C	Iclass: ≤±5% IIclass: ≤±10%	Pressure speed: 1±0.5mm/sec. Measurements should be made in the bent state.																	
temperature cycle	Exterior	no visible damage	preprocessing (IIkind):150+0/-10°C,1hrs,placetwenty four±2hrsafter initial measurement Cycles:5times, a cycle is divided into the following4step: <table><tr><td>stage</td><td>temperature °C</td><td>time (minutes)</td></tr><tr><td>No.1step</td><td>Lower category temperature</td><td>30</td></tr><tr><td>No.2step</td><td>20±2</td><td>3</td></tr><tr><td>No.3step</td><td>upper category temperature</td><td>30</td></tr><tr><td>No.4step</td><td>20±2</td><td>3</td></tr></table>			stage	temperature °C	time (minutes)	No.1step	Lower category temperature	30	No.2step	20±2	3	No.3step	upper category temperature	30	No.4step	20±2	3
	stage	temperature °C				time (minutes)														
	No.1step	Lower category temperature				30														
	No.2step	20±2				3														
	No.3step	upper category temperature				30														
No.4step	20±2	3																		
Δ C/C	Iclass: ≤±1%or±1pF whichever is greater IIclass:X7R X5R≤±10% Z5U Y5V≤±20%																			
DF	same as original standard																			
IR	same as original standard	Placed indoors after the test24±2hrsMeasure again.																		
Steady State Humidity Test	Exterior	no visible damage	temperature:40±2°C humidity:90~95%RH time:500+24/-0Hour Storage conditions: room temperature Placement time:twenty fourHour(Ikind);48Hour(IIkind)																	
	Δ C/C	IClass: ≤±2% or ±1pF whichever is greater IIclass: X7R X5R≤±10% Z5U Y5V≤±30%																		
	DF	≤2times initial standard																		
	IR	IClass:Ri≥2500MΩorR*C _R >25S take the lesser of the two IIclass:Ri≥1000MΩorR*C _R >25S take the lesser of the two																		
life test	Exterior	no visible damage	<table><tr><td>Rated voltage</td><td>Applied voltage</td></tr><tr><td>Ur<500V</td><td>2UR</td></tr><tr><td>500V≤Ur≤1000V</td><td>1.5Ur</td></tr><tr><td>Ur>1000V</td><td>1.2Ur</td></tr></table> Charge and discharge current: ≤50mA Temperature: upper class temperature Time: 96±4 hours Storage conditions: room temperature Placement time:twenty fourHour(Ikind);48Hour(IIkind)			Rated voltage	Applied voltage	Ur<500V	2UR	500V≤Ur≤1000V	1.5Ur	Ur>1000V	1.2Ur							
	Rated voltage	Applied voltage																		
	Ur<500V	2UR																		
	500V≤Ur≤1000V	1.5Ur																		
	Ur>1000V	1.2Ur																		
Δ C/C	IClass: ≤±2% or ±1pF whichever is greater IIclass:X7R X5R≤±20% Z5U Y5V≤±30%																			
DF	≤2times initial standard																			
IR	IClass:Ri≥4000MΩorR*C _R >40S take the lesser of the two IIclass:Ri≥2000MΩorR*C _R >50S take the lesser of the two																			

*** Notes:**

1. Pretreatment (only for class II capacitors):

After the capacitor has been exposed to the upper category temperature or a higher temperature as may be specified in the detail specification for 1 h, it is then recovered for 24 ± 1 h under the standard atmospheric conditions of the test.

2. When testing the dielectric strength of the capacitor, in order to exclude the influence of the external environment, when the test voltage exceeds 2000Vdc, the capacitor should be soaked in insulating oil for testing.

Precautions for use

1. Precautions before use:

The MLCC/MLCV chip may be damaged under the harsh working environment or external mechanical overpressure that exceeds the operating conditions described in the relevant instructions of this acknowledgment.

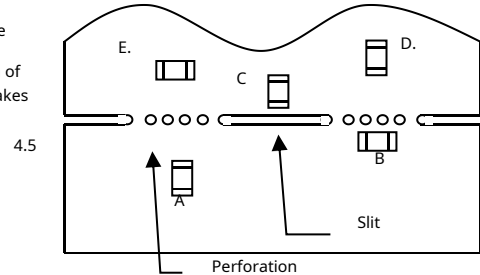
2. PC board design

2.1 The amount of solder used will affect the ability of the chip to resist mechanical stress, which may cause

MLCC/MLCV to break or crack. Therefore, when designing the substrate, the size and configuration of the pad must be carefully considered, which have a decisive effect on the amount of solder that makes up the substrate.

2.2 When designing the position of the pad and SMD MLCC/MLCV, the stress should be minimized, and the MLCC/MLCV should be installed on the least affected position on the PC board.

recommended layout



Stress value: A>B=C>D>E

3. Issues that should be considered in automatic installation

If the pick-up tube is lowered beyond the minimum limit, it will cause excessive pressure on the MLCC/MLCV, which will cause the MLCC/MLCV to rupture. When lowering the pick-up tube, note the following points:

3.1 After correcting the deviation of the PC board, the low limit of the pick-up tube should be adjusted to the surface level of the PC board.

3.2 The suction pressure should be adjusted to between 1 and 3N.

3.3 In order to reduce the deformation of the PC board caused by the impact force of the pick-up tube, the supporting nails should be placed under the PC board.

4. Welding

4.1 MLCC/MLCV is a combination of ceramic and metal. As

ceramic bodies, especially large-scale ceramic bodies, The thermoplastic itself is poor, and the response to heat is relatively slow. Under the condition of rapid cooling and rapid heating, the ceramic body is easy to crack. It is recommended to perform continuous preheating for more than 1 minute before welding.

4.2 The interior of MLCC/MLCV is a metal electrode, which has good thermoplasticity and responds quickly to heat. Thus, in In the case of heat, the metal part and the ceramic part must exist Inconsistencies in expansion to a certain extent, resulting in internal

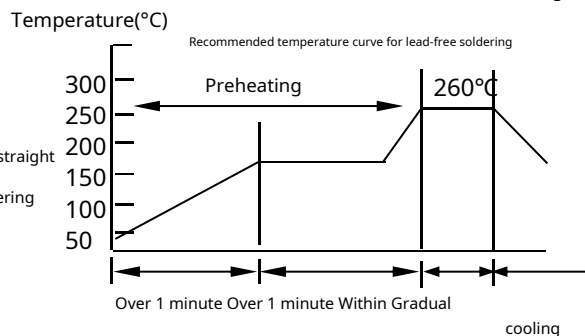
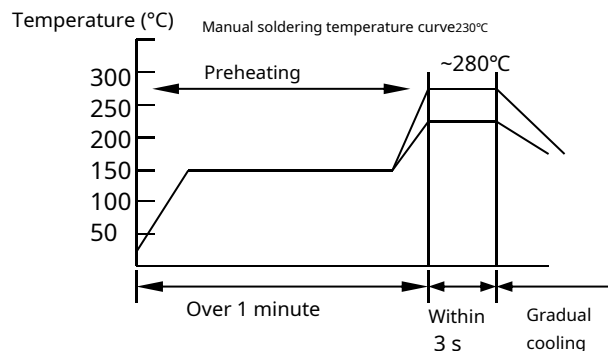
Internal stress can easily cause the porcelain body to crack. It is recommended that before soldering

Perform continuous preheating over 1 minute.

4.3 When manual soldering, use a constant temperature soldering iron with a pointed straight

The maximum diameter is 1.0mm, and the maximum power is 25 watts; the soldering iron cannot touch the MLCC/MLCV components directly.

4.4 It is recommended to avoid wave soldering for specifications above 1206.



5. Cleaning

5.1 The temperature difference between the components and the cleaning process should not exceed 100°C.

5.2 In the case of ultrasonic cleaning, if the output power is too large, the PC board will be subjected to excessive vibration, which will cause MLCC/MLCV or Solder joints are cracked, or terminal electrode strength is reduced. Therefore, pay special attention to the following points: Ultrasonic output: less than 20W/L; ultrasonic frequency: less than 40KHz; ultrasonic cleaning time: 5 minutes or less

6. Cutting the PC board

6.1 After installing MLCC/MLCV and other components, when splitting the PC board, be careful not to exert any force on the board. Do not subject MLCC/MLCV to excessive mechanical shock.

6.2 Segmentation of boards shall not be performed by hand, but with appropriate equipment.

7. Storage method

In order to maintain the solderability of the terminal electrodes and ensure that the packaging materials are in good condition, the recommended storage conditions are as follows: Storage temperature: 5-40°C; Storage relative humidity: 20-70%RH

Even if stored under ideal storage conditions, the solderability of MLCC/MLCV terminals will decrease over time, so MLCC/MLCV should be used within 6 months from the date of shipment.